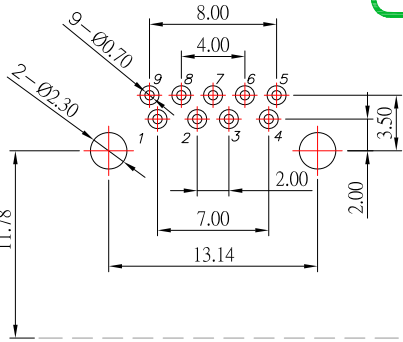




SUA-110H7C-32x-S277

鍍層厚度 :

Blank : 1u"
2 : 15u"
3 : 30u"



RECOMMENDED PCB LAYOUT
TOP VIEW

NOTE:

1.MATERIAL:

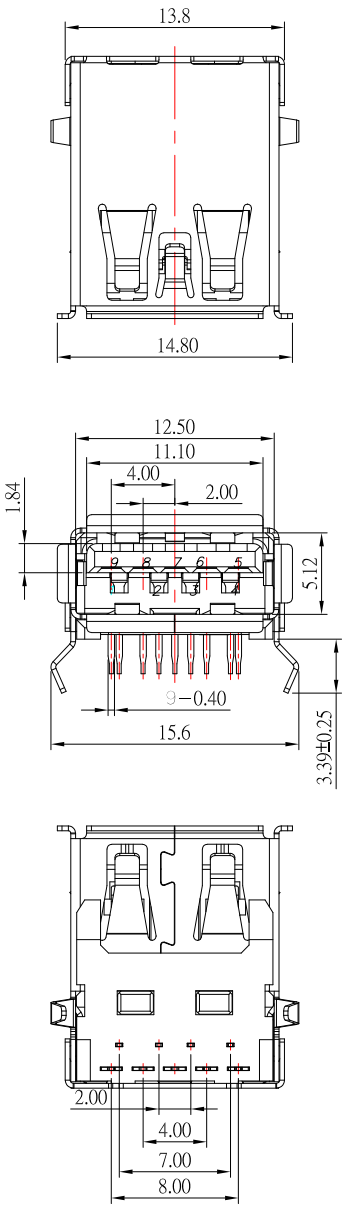
- 1.1 Housing: LCP
- 1.2 Contact: 5Pin:Brass ; 4Pin:Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rating: 3.0A
- 3.2 Insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Operation Temperature: -40°C ~ +85°C



 广东科斯达电子科技有限公司
GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao
DATE: 07/15/24
DATE: 07/15/24
DATE: 07/15/24

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	USB AF 3.1 插板 捲邊 膠芯正向 外殼彎脚
SCALE	DWG NO.	SUA-110H7C-32x-S277
SHEET NO.	PART NO.	SUA-110H7C-32x-S277
		SIZE: A4
		VER: R1